

REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Update to reflect latest changes in format and requirements. Editorial changes throughout. -les	00-12-21	Raymond Monnin
B	Add L package. Editorial changes throughout. -les	01-01-29	Raymond Monnin
C	Update drawing to current requirements. Editorial changes throughout. - gap	08-06-12	Robert M. Heber

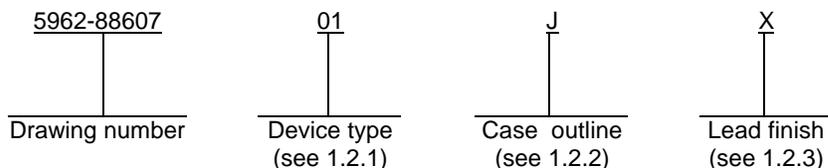
The original first sheet of this drawing has been replaced.

REV																				
SHEET																				
REV																				
SHEET																				
REV STATUS	REV	C	C	C	C	C	C	C	C	C	C	C	C	C	C					
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12							
PMIC N/A	PREPARED BY Larry T. Gauder		<p align="center">DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990 http://www.dsc.dla.mil</p> <p>MICROCIRCUIT, DIGITAL, BIPOLAR, LOW POWER SCHOTTKY TTL, 16-BIT, PARALLEL-IN, SERIAL-OUT, SHIFT REGISTER, MONOLITHIC SILICON</p>																	
<p align="center">STANDARD MICROCIRCUIT DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p align="center">AMSC N/A</p>	CHECKED BY Raymond Monnin																			
	APPROVED BY Michael A. Frye																			
	DRAWING APPROVAL DATE 88-05-18																			
	REVISION LEVEL C	SIZE A	CAGE CODE 67268	5962-88607																
		SHEET 1 OF 11																		

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54LS674	16-bit, parallel-in, serial-out shift register, three-state output

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
J	GDIP1-T24 or CDIP2-T24	24	Dual-in-line
K	GDIP2-F24 or CDFP3-F24	24	Flat package
L	GDIP3-T24 or CDIP4-T24	24	Dual-in-line
3	CQCC1-N28	28	Square leadless chip carrier

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings. ^{1/}

Supply voltage	-0.5 V dc to +7.0 V dc
Input voltage:	
SER/Q15 input	-1.5 V dc at -18mA to +5.5 V dc
All other inputs	-1.5 V dc at -18mA to +7.0 V dc
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P _D) ^{2/}	220 mW ^{2/}
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ _{JC})	See MIL-STD-1835
Junction temperature (T _J)	+175°C

^{1/} Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

^{2/} Maximum power dissipation is defined as V_{CC} x I_{CC}, and must withstand the added P_D due to short circuit test; e.g., I_{OS}.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 2

1.4 Recommended operating conditions.

Supply voltage range (V_{CC})	+4.5 V dc to +5.5 V dc
Minimum high-level input voltage (V_{IH})	+2.0 V dc
Maximum low level input voltage (V_{IL})	0.7 V dc
Case operating temperature range (T_c)	-55°C to +125°C
Minimum width of input clock pulse (t_{WCLK})	20 ns
Minimum width of input clock pulse (t_{WCLR})	20 ns
Minimum setup time (t_s):	
SER/Q15	20 ns
MODE	35 ns
R/\overline{W} , \overline{CS}	35 ns
P0-P15	20 ns
Minimum hold time (t_h):	
P0-P15	5.0 ns
Other inputs	0 ns

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 3

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table. The truth table shall be as specified on figure 2.

3.2.4 Switching waveforms and test circuit. The switching waveforms and test circuit shall be as specified on figure 3.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 4

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C 4.5 V ≤ V _{CC} ≤ 5.5 V unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
High level output voltage	V _{OH}	V _{CC} = +4.5 V, V _{IL} = 0.7 V, V _{IH} = +2.0 V	SER/Q15 I _{OH} = -0.1 mA	1, 2, 3	2.4		V
Low level output voltage	V _{OL}	V _{CC} = +4.5 V, V _{IL} = 0.7 V, V _{IH} = +2.0 V	SER/Q15 I _{OL} = 4 mA	1, 2, 3		0.4	V
Input clamp voltage	V _{IC}	I _{IN} = -18 mA, V _{CC} = +4.5 V		1, 2, 3		-1.5	V
High level input current	I _{IH1}	V _{CC} = +5.5 V	V _{IN} = +5.5 V SER/Q15	1, 2, 3		0.1	mA
			V _{IN} = +7.0 V All other inputs	1, 2, 3		0.1	mA
	I _{IH2}	V _{CC} = +5.5 V, V _{IN} = +2.7 V	SER/Q15	1, 2, 3		40	μA
			All other inputs	1, 2, 3		20	μA
Off-state output current	I _{OZH}	V _{CC} = +5.5 V, V _{IH} = +2.0 V, V _{IL} = +0.7 V, V _{OUT} = +2.7 V	SER/Q15	1, 2, 3		40	μA
	I _{OZL}	V _{CC} = +5.5 V, V _{IH} = +2.0 V, V _{IL} = +0.7 V, V _{OUT} = +0.4 V		1, 2, 3		-0.4	mA
Low level input current	I _{IL}	V _{CC} = +5.5 V, V _{IN} = 0.4 V		1, 2, 3		-0.4	mA
Short-circuit output current	I _{OS}	V _{CC} = +5.5 V <u>1/</u>	SER/Q15	1, 2, 3	-30	-130	mA
Supply current	I _{CC}	V _{CC} = +5.5 V		1, 2, 3		40	mA
Functional tests		See 4.3.1c		7, 8			

See footnotes at end of table.

**STANDARD
MICROCIRCUIT DRAWING**
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43218-3990

SIZE
A

REVISION LEVEL
C

5962-88607

SHEET
5

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C 4.5 V ≤ V _{CC} ≤ 5.5 V unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Maximum clock frequency, CLK to SER/Q15	f _{MAX}	V _{CC} = 5.0 V, C _L = 50 pF, 2/ R _L = 667 Ω ±5%	9	20		MHz
			10, 11	12		
Propagation delay time, CLK to SER/Q15	t _{PLH}	See figure 3	9	5	33	ns
			10, 11	5	47	
	t _{PHL}		9	5	40	ns
			10, 11	5	57	
Output enable time, CS̄, R/W̄ to SER/Q15	t _{PZH}		9	5	45	ns
			10, 11	5	64	
	t _{PZL}		9	5	45	ns
			10, 11	5	64	
Output disable time, CS̄, R/W̄ to SER/Q15	t _{PHZ}		9	5	44	ns
			10, 11	5	61	
	t _{PLZ}		9	5	44	ns
			10, 11	5	61	

1/ Not more than one output shall be shorted at a time, and the duration of the short-circuit condition shall not exceed one second.

2/ Propagation delay time testing may be performed using either C_L = 5, 45 or 50 pF. However, the manufacturer must certify and guarantee that the microcircuit meets the switching test limits specified for a 50 pF load.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 6

Case outlines	J, K, and L	3
Terminal number	Terminal connection	
1	\overline{CS}	NC
2	CLK	\overline{CS}
3	R/\overline{W}	CLK
4	NC	R/\overline{W}
5	Mode	NC
6	SER/Q15	Mode
7	P0	SER/Q15
8	P1	NC
9	P2	P0
10	P3	P1
11	P4	P2
12	GND	P3
13	P5	P4
14	P6	GND
15	P7	NC
16	P8	P5
17	P9	P6
18	P10	P7
19	P11	P8
20	P12	P9
21	P13	P10
22	P14	NC
23	P15	P11
24	V_{CC}	P12
25		P13
26		P14
27		P15
28		V_{CC}

NC = No connection

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 7

Inputs				SER/Q15	Operation
\overline{CS}	R/\overline{W}	Mode	CLK		
H	X	X	X	Z	No change
L	L	X	↓	Z	Shift and write serial load
L	H	L	↓	Q14n	Shift and read
L	H	H	↓	P15	Parallel load

L = Low level (steady state)

H = High level (steady state)

↓ = transition from high to low level

X = irrelevant

Z = Off-state (high impedance) of a 3-state output

Q14n = content of 14th bit of the shift register before the most recent ↓ transition of the clock.

P15 = level of input P15

FIGURE 2. Truth table.

**STANDARD
MICROCIRCUIT DRAWING**
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43218-3990

SIZE
A

5962-88607

REVISION LEVEL
C

SHEET
8

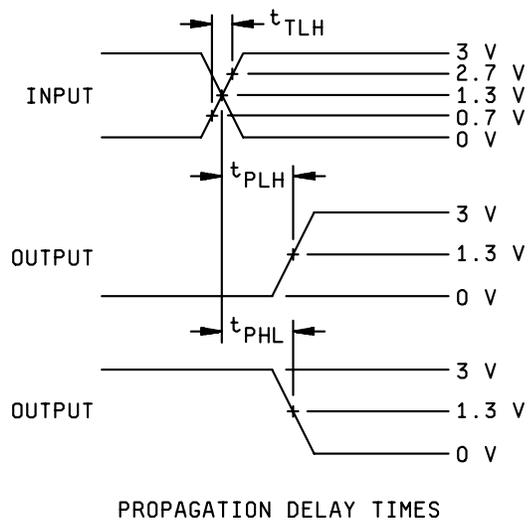
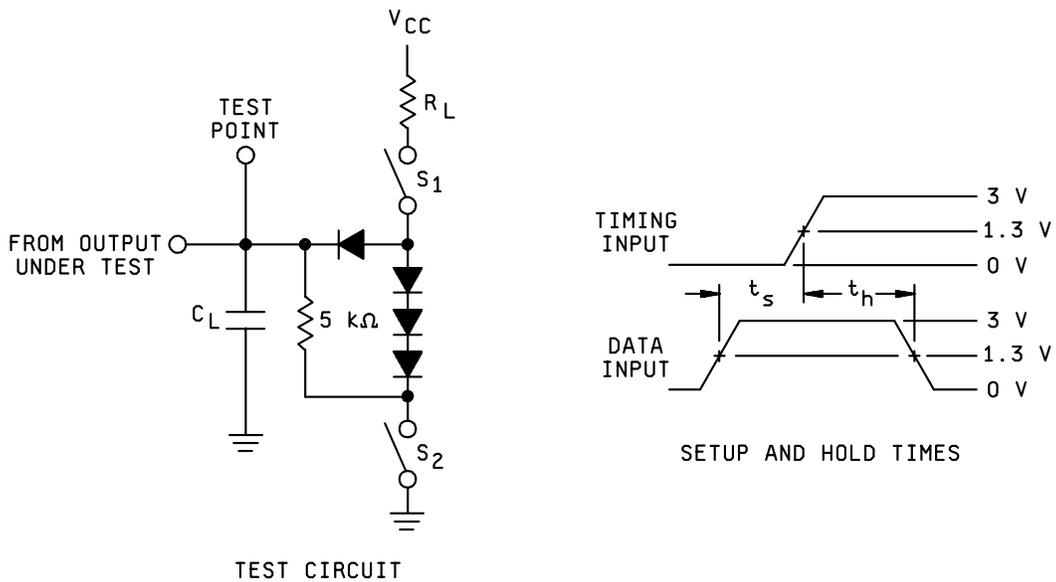


FIGURE 3. Switching waveforms and test circuit.

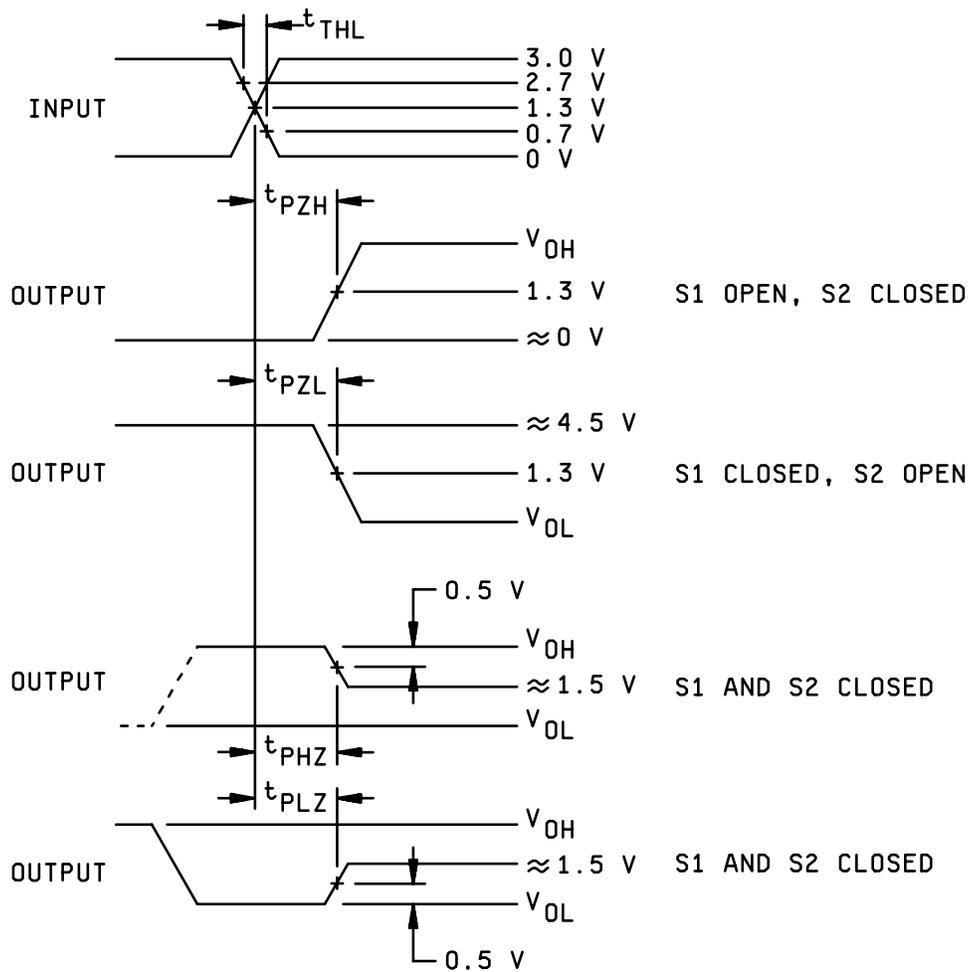
**STANDARD
MICROCIRCUIT DRAWING**
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43218-3990

SIZE
A

5962-88607

REVISION LEVEL
C

SHEET
9



ENABLE AND DISABLE TIMES

NOTES:

1. The pulse generator shall have the following characteristics: $PRR \leq 1.0 \text{ MHz}$, $t_{TLH} \leq 15 \text{ ns}$, $t_{THL} \leq 6 \text{ ns}$.
2. $C_L = 50 \text{ pF} \pm 10\%$ including scope probe, wiring, and stray capacitance without the package in the test fixture.
3. $R_L = 667 \Omega \pm 5\%$.
4. All diodes are 1N3064, 1N916 or equivalent.

FIGURE 3. Switching waveforms and test circuit - Continued.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 10

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

- (1) Test condition A, D, E, or F. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
- (2) $T_A = +125^\circ\text{C}$, minimum for test condition A, D, or E.
 $T_A = +175^\circ\text{C}$, minimum for test condition F.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

** Subgroups 10 and 11 if not tested, shall be guaranteed to the specified limits in table I.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 7 and 8 shall include verification of the truth table.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 11

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, D, E, or F. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum for test condition A, D, or E.
 $T_A = +175^{\circ}\text{C}$, minimum for test condition F.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0547.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE A		5962-88607
		REVISION LEVEL C	SHEET 12

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 08-06-12

Approved sources of supply for SMD 5962-88607 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at <http://www.dscclia.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-8860701JA	01295	SNJ54LS674J
5962-8860701KA	01295	SNJ54LS674W
5962-8860701LA	01295	SNJ54LS674JT
5962-88607013A	01295	SNJ54LS674FK

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

01295

Vendor name
and address

Texas Instruments, Inc.
Semiconductor Group
8505 Forest Lane
PO Box 660199
Dallas, TX 75243

POC U.S. Highway 75 South
P.O. Box 84, M/S 853
Sherman, TX 75090-9493

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.